



深圳市泰河电子有限公司

SHENZHEN TH ELECTRONICS CO;LTD

产品确认书

Product Confirmation

CUSTOMER: _____

Product :

声表面谐振器

Frequency:

R315M

Model:

D11— DIP

DATE: _____

承认后请寄回一份

PLS SEND BACK ONE COPY TO US AFTER YOUR APPROVAL

| 承认结果 CONCLUSION | 客户签名 SIGNATURE | 客户承认章 STAMP | 日期 DATE | 备注 REMARK |
|--------------------|-------------------|----------------|------------|--------------|
| 合格 ACCEPT | | | | |
| 不合格 REJECT | | | | |

制表: 刘小姐 _____

审核: _____

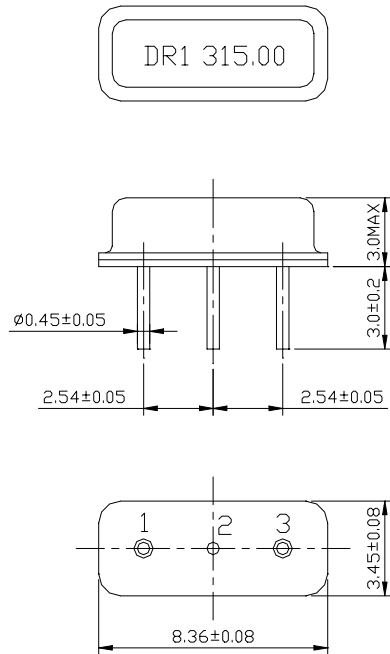
(公章)

尊敬的客户: 请您抽出一点时间, 在7-10个工作日内将承认书回签, 若未回签, 以视默认. 谢谢合作!

TH R315M 声表面谐振器D11 DIP

1. Package Dimension (D11)

Unit: mm



Bottom View

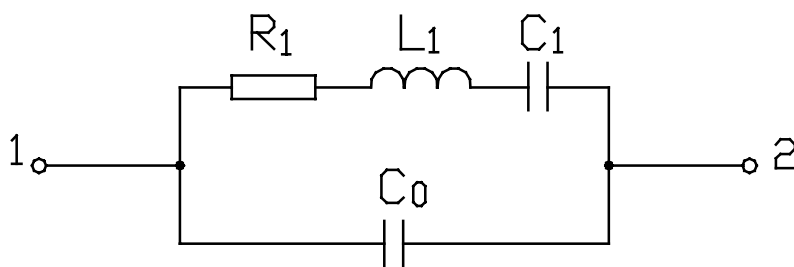
| Pin No. | Function |
|---------|----------|
| 1. | Input |
| 2. | Ground |
| 3. | Output |

2. Marking

TH 315.00

1. Color: Black or Blue
2. D: Manufacture's logo
3. R1: One-port SAW Resonator
4. 315.00: Center Frequency (MHz)

3. Equivalent LC Model



TH R315M 声表面谐振器D11 DIP

4. Performance

4.1 Maximum Rating

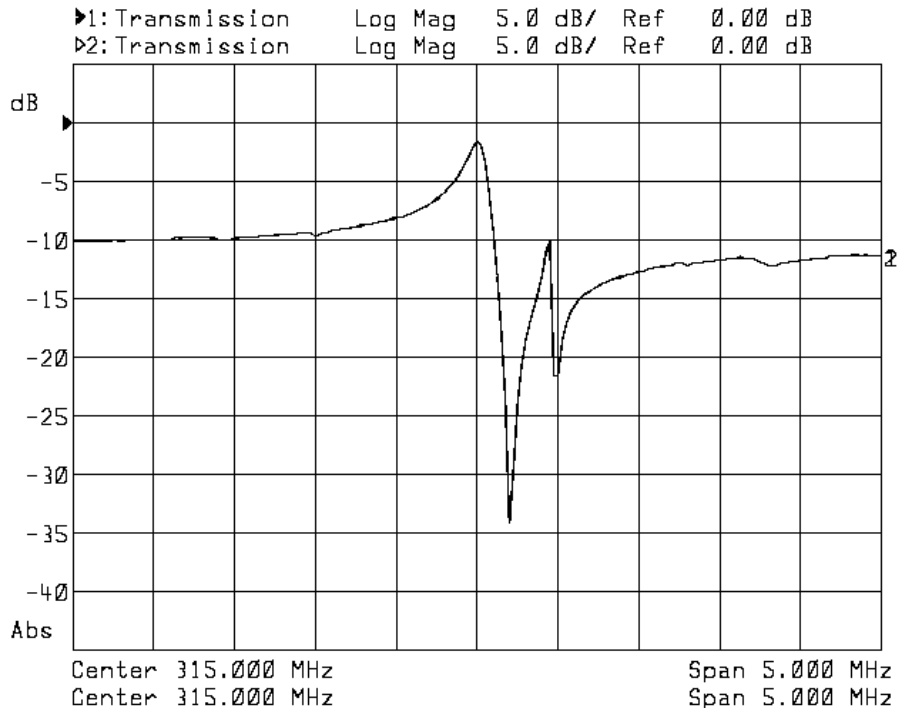
| | |
|-----------------------|-----------------|
| DC Voltage V_{DC} | 10V |
| AC Voltage V_{PP} | 10V (50Hz/60Hz) |
| Operation Temperature | -40 to +85 |
| Storage Temperature | -45 to +85 |
| RF Power Dissipation | 0dBm |

4.2 Electronic Characteristics

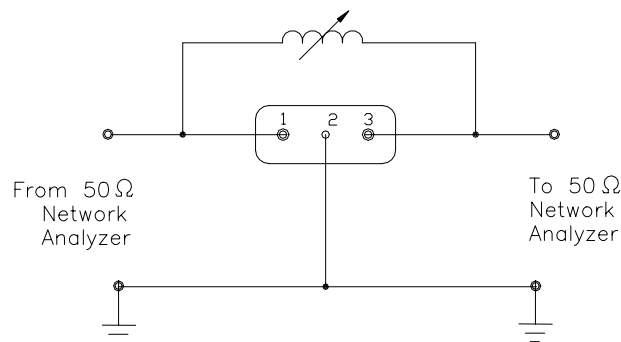
| Item | | Units | Minimum | Typical | Maximum |
|----------------------------|--------------------------------|---------|---------|------------|---------|
| Center Frequency f_0 | | MHz | 314.925 | 315 | 315.075 |
| Insertion Loss | | dB | — | 1.3 | 2.5 |
| Quality Factor | Unloaded Q | — | — | 12,000 | — |
| | 50 Loaded Q | — | — | 1,900 | — |
| Temperature | Turnover Temperature | | 10 | 25 | 40 |
| Stability | Turnover Frequency | KHz | — | f_0 | — |
| | Freq.Temp.Coefficient | ppm/°C | — | 0.037 | — |
| Frequency Aging | | ppm/yr | — | $< \pm 10$ | — |
| DC Insulation Resistance | | M | 1.0 | — | — |
| RF Equivalent RLC Model | Motional Resistance R_1 | | — | 23 | 29 |
| | Motional Inductance L_1 | μH | — | 115.2 | — |
| | Motional Capacitance C_1 | fF | — | 2.2 | — |
| | Shunt Static Capacitance C_0 | pF | 2.1 | 2.4 | 2.7 |

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4.3 Frequency Characteristics



4.4 Test Circuit



Note: Reference temperature shall be 25 ± 2 . However, the measurement may be carried out at 5 to 35 unless there is a dispute.

5. Reliability

5.1 Mechanical Shock: The components shall remain within the electrical specifications after 1000 shocks, acceleration 392 m/s^2 , duration 6 milliseconds.

5.2 Vibration Fatigue: The components shall remain within the electrical specifications after loaded vibration at 20 Hz, amplitude 1.5 mm, for 2 hours.

5.3 Terminal Strength: The components shall remain within the electrical specifications after pulled 2 kgs weight for 10 seconds towards an axis of each terminal.

5.4 High Temperature Storage: The components shall remain within the electrical specifications after being kept at the 85 ± 2 for 48 hours, then kept at room temperature for 2 hours.

5.5 Low Temperature Storage: The components shall remain within the electrical specifications after being kept at the -25 ± 2 for 48 hours, then kept at room temperature for 2 hours.

5.6 Temperature Cycle: The components shall remain within the electrical specifications after 5 cycles of high and low temperature testing (one cycle: 80 for 30 minutes 25 for 5 minutes -25 for 30 minutes)than kept at room temperature for 2 hours.

5.7 Solder-heat Resistance: The components shall remain within the electrical specifications after dipped in the solder at 260 for 10 ± 1 seconds, then kept at room temperature for 2 hours. (Terminal must be dipped leaving 1.5 mm from the case).

5.8 Solder Ability: Solder ability of terminal shall be kept at more than 80% after dipped in the solder flux at 230 ± 5 for 5 ± 1 seconds.

6. Remarks

6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning.

6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.